

| L Number | Hits    | Search Text  | DB  | Time stamp          |
|----------|---------|--|---|---------------------|
| 1        | 116541  | gasket polytetrafluorethylene  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/19<br>05:01 |
| 2        | 25      | (gasket polytetrafluorethylene) same lossy   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/19<br>05:01 |
| 3        | 2858366 | (semiconductor processor microprocessor chip die ic (integrated adj circuit))  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/19<br>05:03 |
| 4        | 430180  | heat with (dissipate sink spreader slug element metal)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/19<br>05:04 |
| 5        | 420607  | eds electrostatic electro-static (electro adj3 static)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/19<br>05:05 |
| 6        | 26672   | (eds electrostatic electro-static (electro adj3 static)) with (discharge discharging)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/19<br>05:05 |
| 7        | 503     | (gasket polytetrafluorethylene) and ((semiconductor processor microprocessor chip die ic (integrated adj circuit))) and (heat with (dissipate sink spreader slug element metal)) and (eds electrostatic electro-static (electro adj3 static))  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/19<br>05:05 |
| 8        | 44      | (gasket polytetrafluorethylene) and ((semiconductor processor microprocessor chip die ic (integrated adj circuit))) and (heat with (dissipate sink spreader slug element metal)) and ((eds electrostatic electro-static (electro adj3 static)) with (discharge discharging))   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/19<br>05:24 |
| 9        | 459     | ((gasket polytetrafluorethylene) and ((semiconductor processor microprocessor chip die ic (integrated adj circuit))) and (heat with (dissipate sink spreader slug element metal)) and (eds electrostatic electro-static (electro adj3 static))) not ((gasket polytetrafluorethylene) and ((semiconductor processor microprocessor chip die ic (integrated adj circuit))) and (heat with (dissipate sink spreader slug element metal)) and ((eds electrostatic electro-static (electro adj3 static)) with (discharge discharging))) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/19<br>05:24 |

|    |     |  |   |                     |
|----|-----|--|---|---------------------|
| 10 | 127 | (((gasket polytetrafluorethylene) and ((semiconductor processor microprocessor chip die ic (integrated adj circuit))) and (heat with (dissipate sink spreader slug element metal)) and (eds electrostatic electro-static (electro adj3 static))) not ((gasket polytetrafluorethylene) and ((semiconductor processor microprocessor chip die ic (integrated adj circuit))) and (heat with (dissipate sink spreader slug element metal)) and ((eds electrostatic electro-static (electro adj3 static)) with (discharge discharging)))) and package | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/19<br>05:24 |
|----|-----|--|---|---------------------|